

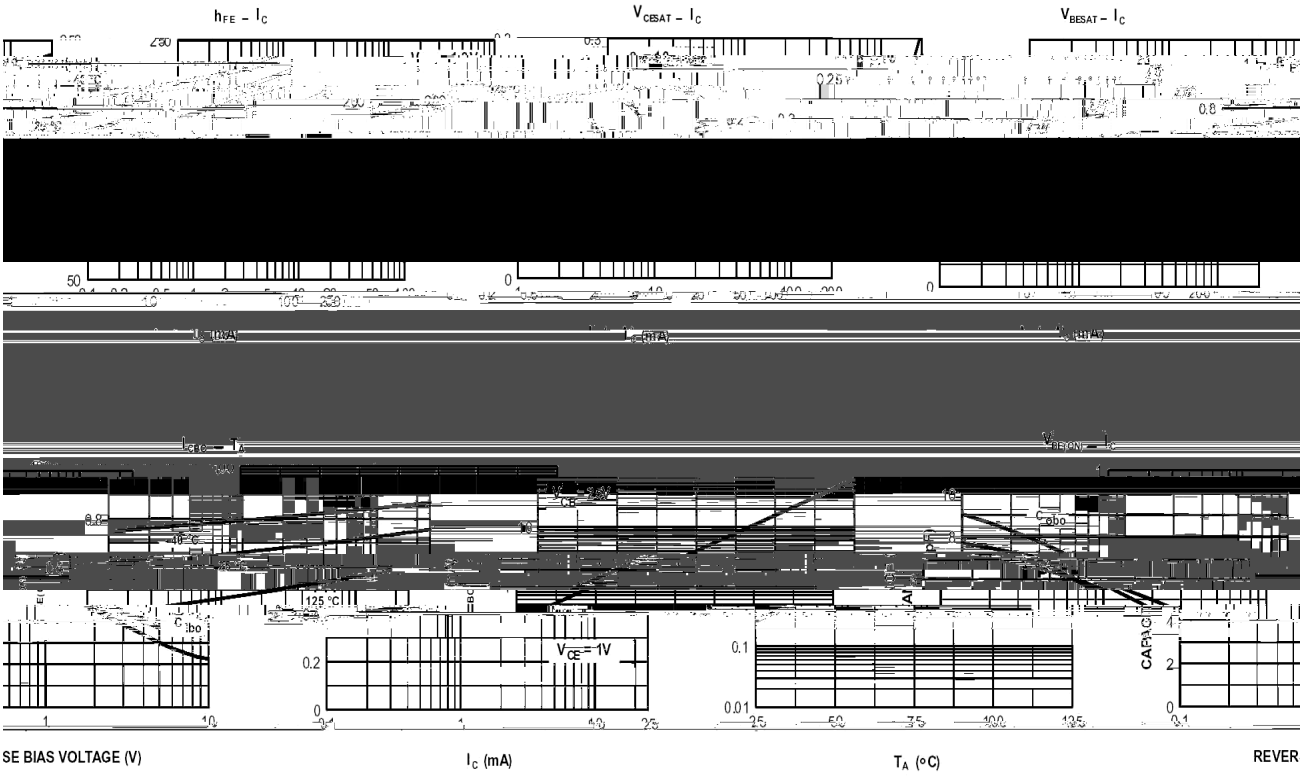
MMBT3906

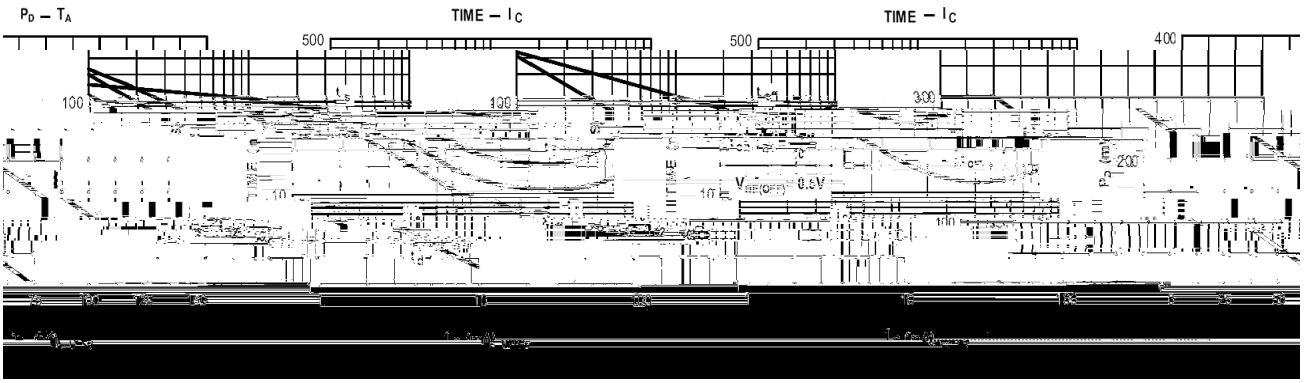
i j Parameter	k l Symbol	j m Rating	n o Unit
Collector to Base Voltage	V_{CBO}	-40	V
Collector to Emitter Voltage	V_{CEO}	-40	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current	I_C	-200	mA
Collector Power Dissipation	P_C	300	mW
Junction Temperature	T_j	150	℃
Storage Temperature Range	T_{stg}	-55～150	℃

i j Parameter	k l Symbol	p q r s Test Conditions	t u m Min	v w m T

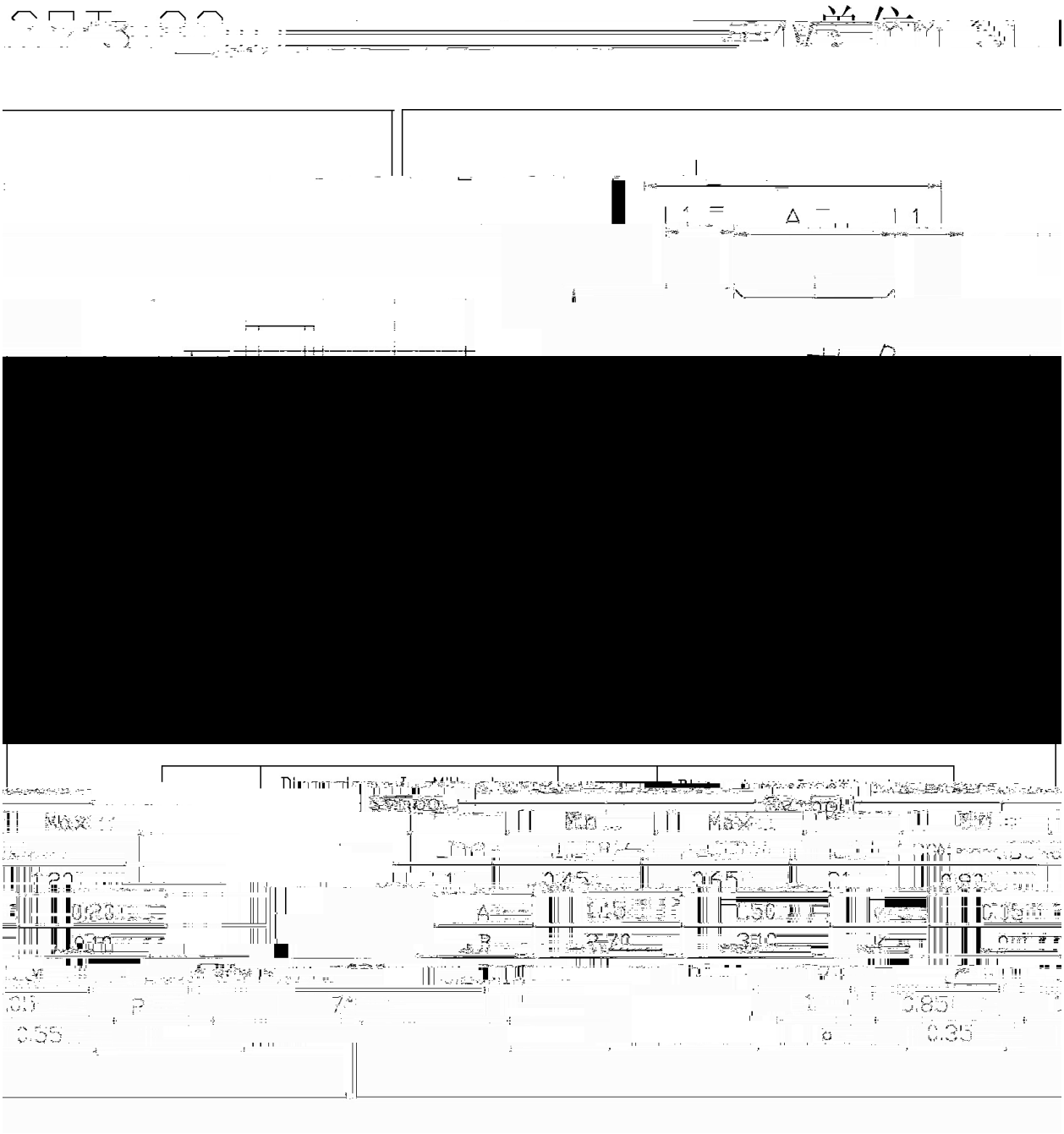
i j

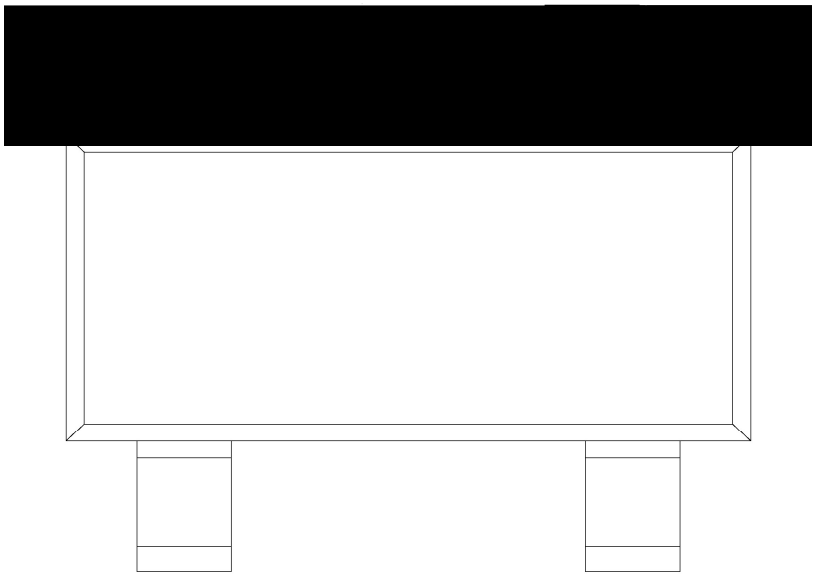
/ Electrical Characteristic Curve



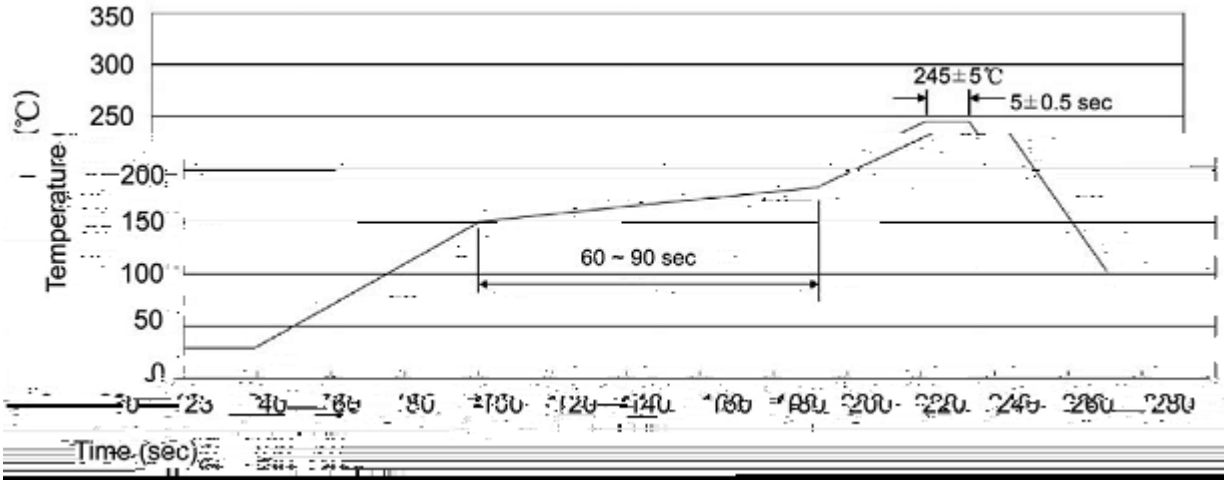


/ Package Dimensions





( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



						Note:	
1		25	150		60 90sec;	1.Preheating:25~150	, Time:60~90sec.
2		245±5			5±0.5sec;	2.Peak Temp.:245±5	, Duration:5±0.5sec.
3				2 10	/sec.	3. Cooling Speed: 2~10	/sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5℃	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type !	Units " # $	Dimension " % & (unit ' mm^3)